MULTI LAYER CERAMIC CAPACITORS

- GML SERIES -

DE

DESCRIPTION

- MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.
- CCE GML series MLCC is used in product having thickness concerned generally have high capacitance and thinner product thickness. The high dielectric constant material X7R and X5R are used for this series product.

FEATURES

- Standard size with thin thickness.
- Small size with high capacitance.
- Capacitor with lead-free termination (pure Tin).



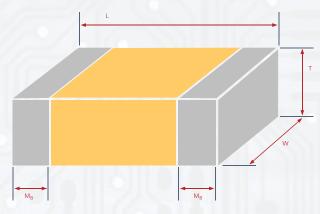
APPLICATIONS

- For LCD panels.
- For PCMCA cards.
- For IC packaging and modules.
- Any thickness concerned products.



ORDERING INFORMATION





SIZE INCH (MM)	L (MM)	W (MM)	T (MM) SYMBO		M _B (MM)
0402 (1005)	1.00 ± 0.2	0.5 ± 0.2	0.30 ± 0.03	L	0.25 ± 0.10
0603 (1608)	1.6 +15 / -0.10	0.8+ 0.15 / - 0.10	0.50 ± 0.10	Н	0.40 ± 0.15
0805 (2012)	2.00 ± 0.20	1.25±0.20	0.85 ± 0.10	Т	0.50 ± 0.20
1206		4.40 0.00	0.85 ± 0.10	Т	0.40 0.00
(3216)	3.20 ± 0.20	1.60 ± 0.20	1.15 ± 0.15	J	0.60 ± 0.20
1210	2.20 . 0.20	2.50.0.20	0.85 ± 0.10	Т	0.75 . 0.05
(3225)	3.20 ± 0.30	2.50±0.20	2.00 ± 0.20	К	0.75 ± 0.25

GML	21	X5R	475	K	6R3	N	Т	
SERIES	SIZE	DIELECTRIC	CAPACITANCE	TOLERANCE	VOLTAGE	TERMINATION	PACKAGING	
GML - Low Profile	04 - 0402 (1005) 10 - 0603 (1608) 21 - 0805 (2012) 31 - 1206 (3216) 32 - 1210 (3225)	X7R X5R	Two significant digits followed by no. of zeros. And R is in place of decimal point.	K: ±10% M: ±20%	Two significant digits followed by no. of zeros. And R is in place of decimal point.	N: Cu / Ni / Sn	T: 7" reeled G: 13" reeled	
			eg.: 475 =47×105 =4,700,000 pF =4.7µF		6R3: 6.3 VDC 10: 10 VDC 16: 16 VDC 25: 25 VDC 50: 50 VDC 100: 100 VDC			

GENERAL ELECTRICAL DATA

DIELECTRIC	X7R	X5R			
SIZE	0402, 0603, 0805	, 1206, 1210			
CAPACITANCE RANGE*	1μF to 10μF	0.22μF to 47μF			
CAPACITANCE TOLERANCE**	K (±10%), M	(±20%)			
RATED VOLTAGE	10V, 16V, 25V, 50V, 100V	6.3V, 10V, 16V, 25V			
OPERATING TEMPERATURE	-55 to +125°C	-55 to +85°C			
CAPACITANCE CHARACTERISTIC	±15%				
TERMINATION	Ni / Sn (lead-free	termination)			

^{*} Measured at 1.0 \pm 0.2Vrms, 1.0kHz \pm 10%, 30~70% related humidity, 25°C ambient temperature for X7R, X5R. ** Preconditioning for Class II MLCC: Perform a heat treatment at 150 \pm 10°C for 1 hour, then leave in ambient condition for 24 \pm 2 hours before measurement





CAPACITANCE RANGE

- X7R DIELECTRIC

	DIELECT	ΓRIC						X7R		7			
	SIZE			08	05			12	06	0		1210	
F	RATED VO	LTAGE	10	16	25	50	10	16	25	50	10	16	100
	1.0uF	105											
E E	1.5uF	155				m				77			
RANGE	2.2uF	225		Т	Т								К
ICE	3.3uF	335		7/1									
ITAN	4.7uF	475	Т				717						
CAPACITANCE	6.8uF	685											
CA	10uF	106					Т						
	22uF	226											

- X5R DIELECTRIC

	DIELECT	RIC				7				1	X	5R	410							
	SIZE		4	0402			0603			08	05				1206				1210	
F	RATED VO	LTAGE	6.3	10	25	6.3	10	16	6.3	10	16	25	6.3	10	16	25	50	10	16	25
П	0.22uF	224			L		н	Н												
Ш	0.47uF	474	F	1	L					l.	1									
111	1.0uF	105	L				н	Н												
CAPACITANCE RANGE	1.5uF	155																		
E R/	2.2uF	225	L																	
ANC	3.3uF	335																		
4C∏	4.7uF	475	L				Н													
CAP,	6.8uF	685							1											
	10uF	106				G								J/T		Т				Т
	22uF	226																		
	47uF	476																		

PACKAGING STYLE AND REEL SIZE

CIZE	THICKNES:	S MASS	7"	REEL
SIZE	(MM) / SY	MBOL	PAPER TAPE	PLASTIC TAPE
0402 (1005)	0.22	F	10k	
0402 (1005)	0.33	L	15k	
0603 (1608)	0.50	g	4k	11/200
0603 (1608)	0.60	Н	4k	
0805 (2012)	0.95	Т	4k	1/4
1207 (2217)	0.95	Т	4k	
1206 (3216)	1.30	J		3k
1210 (2225)	0.95	Т	<u> </u>	3k
1210 (3225)	2.00	K		1k







RELIABILITY TEST CONDITIONS AND REQUIREMENTS

NO.	ITEMS	TES	T COI	NDITION		REQUI	REMENTS
1.	Visual and Mechanical				- No remarkal		dividual specification sheet.
2.	Capacitance	- Test temp.: Room Temp	erature	. 14/34/7	- Shall not ex	ceed the limits gi	iven in the detailed spec.
3.		Cap≤10μF, 1.0±0.2Vrms, Cap>10μF, 0.5±0.2Vrms,			X7R / X5R:		
٥.	0/05					RATED VOL.	D.F.
	Q/ D.F. (Dissipation	** Test condition: 0.5±0.2 GML10 X5R ≥475(10V) ,				100V	≤5%
	Factor)	*Poforo initial managerom	ont (Cla	ss II only): To apply de-aging at		50V, 25V, 16V, 10V	′ ≤10%
		150°C for 1hr then set fo				6.3V	≤5%
4.	Dielectric Strength	- To apply voltage: 250% - Duration: 1 to 5 sec. - Charge and discharge of			- No evidence	e of damage or f	lash over during test.
5.	Insulation Resistance	- Test temp.: Room Temp - To apply rated voltage			≥10GΩ or Rx	C ≥ 100Ω - F whi	ichever is smaller.
6.		With no electrical load.				TE JJJ.	
		T.C.	OPFI	RATING TEMPERATURE		T.C.	CAPACITANCE CHANGE
		X7R	OI EI	-55~125°C at 25°C		X7R	Within ±15%
		X5R		-55~85°C at 25°C		X5R	Within ±15%
		- Before initial measurem To apply de-aging at 150 room temp. - Measurement voltage fo	°C for 1	hr then set for 24± 2 hrs at			
		0402		0603			
		Cap<1µF: 1V		Cap<1μF: 1V			
	Temperature Coefficient	Cap=1µF: 0.5V* 0402 X7R 224-16V: 0402 X7R 474-10V: 0402 X5R 475M6R3	0.5V 0.5V	1μF≤Cap≤4.7μF: 0.5V 0603 X5R 106-10V: 0.5V			
		1μF <cap<10μf: c<="" td=""><td>0.2V V: 0.2V</td><td>Cap>4.7μF: 0.2V</td><td></td><td></td><td></td></cap<10μf:>	0.2V V: 0.2V	Cap>4.7μF: 0.2V			
M		Cap≥10μF: 0.1\	/				
		0805		1206 / 1210			
		—————————————————————————————————————	,	Сар<10µF: 1V			
		Cap=10µF: 0.5 0805 X7R 475/6.3V~2		10μF <cap≤100μf: 0.5v<="" td=""><td></td><td></td><td></td></cap≤100μf:>			
		Cap>10μF: 0.2	V	Cap>100μF: 0.2V 1206 X5R 107-6.3V: 0.2V			
7.	Adhesive Strength of Termination	- Pressurizing force: 5N (s - Test time: 10±1 sec.	≤ 0603)	and 10N (>0603)	- No remarka	ble damage or re	emoval of the terminations.
8.	Vibration Resistance	- Total amplitude: 1.5mm - Test time: 6 hrs. (Two hr perpendicular directions. - Before initial measurem To apply de-aging at 150 room temp. - Cap./DF(Q) Measureme	me: 6 hrs. (Two hrs each in three mutually dicular directions.) e initial measurement (Class II only): y de-aging at 150°C for 1hr then set for 24± 2 hrs at		- No remarka - Cap change		meet initial spec.
9.	Solderability	- Solder temperature: 23: - Dipping time: 2±0.5 sec				overage of all me	talized area.
10.	Bending Test	pressurized by means of 1 mm per second until th the pressure shall be mai - Before initial measurem To apply de-aging at 150 room temp.	iddle part of substrate shall be zed by means of the pressurizing rod at a rate of about er second until the deflection becomes 1 mm and then ssure shall be maintained for 5±1 sec. initial measurement (Class II only): y de-aging at 150°C for 1hr then set for 24± 2 hrs at			ance underspeci	n ±12.5% ge means the change of fied flexure of substrate easured before the test.)







RELIABILITY TEST CONDITIONS AND REQUIREMENTS

NO.	ITEMS		TEST COND	ITION			REQUIF	REMENTS		
11.	Resistance to Soldering Heat	capacitor in a eu - Before initial m at 150°C for 1hr - Cap. / DF(Q) /	10±1 sec O to 150°C for 1 min	I only): To a rs at room b be made	apply de-aging temp . after de-aging at	- Q/D.F., I.R. a	e: X7R/X5R: withir and dielectric stre	ength: To meet initial		
12.	Temperature Cycle	- Conduct the fix time. STEP 1 2 3 4 - Before initial mat 150°C for 1hr	re cycles according TEMP. (°C) Min. operating temp. Room Temp Max. operating temp. Room Temp easurement (Class I then set for 24±2 h I.R. Measurement to	TIN +0/-3 +3/-0 Il only): To a	peratures and ME (MIN) 30±3 2~3 30±3 2~3 apply de-aging temp.		: X7R/X5R: within and dielectric stre	±7.5% ength: To meet initial		
h			then set for 24±2 h			- No remarka	hle damage			
		T	1200				: X7R/X5R: within	±25%		
		- Test temp.: 40=	95% RH			R	ATED VOL.	D.F.		
13.	Humidity (Damp Heat)	- Test time: 500+	-24/-0hrs. easurement (Class I	I only): To a	apply de-aging		100V	≤7.5%		
10.	Steady State	at 150°C for 1hr	then set for 24±2 h	rs at room	temp.		25V, 16V	≤15%		
			Cap. / DF(Q) / I.R. Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp.				10V	≤20%		
							50V, 6.3V	≤30%		
						- I.R.: 1G Ω or RxC≥10 Ω -F whichever is smaller.				
11			95%RH -24/-0 hrs. je: Rated voltage.			No remarkab *Cap change *Q/D.F. value X7R/X5R:	: X7R/X5R: within	±25%		
	11 . 19		easurement (Class I then set for 24±2 h			R	ATED VOL.	D.F.		
14.	Humidity (Damp Heat)	- Cap. / DF(Q) /	I.R. Measurement to then set for 24±2 h	be made	after de-aging		100V	≤7.5%		
	Load	at 130 C for Thr	uleli set ioi z4±Z N	is at 100III	temp.	NE T	25V, 16V	≤15%		
							10V	≤20%		
							50V, 6.3V	≤30%		
1						- I.R.: 500MΩ	or RxC≥5 Ω-F wh	nichever is smaller.		
		- Test time: 1000 - To apply voltage	R: 125±3°C X5R: 89 0+24/-0 hrs. ge: 150% of rated vo voltage for below ra	oltage.		- No remarkal - Cap change - Q/D.F. value X7R/X5R:	: X7R/X5R: within	±25%		
				RATED	CAPACITANE		RATED VOL.	D.F.		
4.5	High Temperature	SIZE D	IELECTRIC	VOLTAGE	RANGE		100V	≤7.5%		
15.	Load	GML04	X5R	6.3V	C ≥ 1.0 µF		25V, 16V	≤15%		
	(Endurance)	GML21 X5	5R X7R X6S	≤10V	C ≥ 10 µF		10V	≤20%		
		- Before initial m	easurement (Class I	I only): To a	apply de-aging	14///	50V, 6.3V	≤30%		
		* - Cap. / DF(Q)	then set for 24±2 h / I.R. Measurement for 24±2 hrs at room	to ©r de-a		- I.R.: 1GΩ or	RxC≥10Ω-F whic	hever is smaller.		

^{* &}quot;Room condition" Temperature: 15 to 35°C, Relative humidity: 25 to 75%, Atmospheric pressure: 86 to 106kPa.



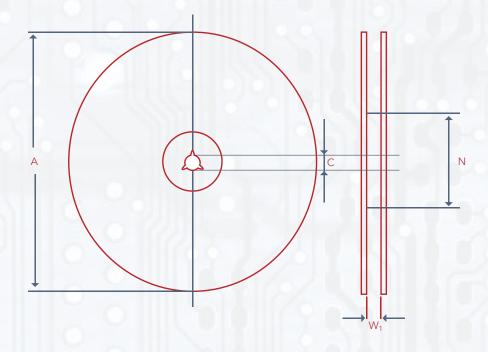




RELIABILITY TEST CONDITIONS AND REQUIREMENTS

NO.	ITEMS		TEST CO	ONDITION	9/		REQUIR	REMENTS
		- Test time - To apply	p.: X7R: 125±3°C X e: 1000+24/-0 hrs. voltage: 150% of rat f rated voltage for be	ted voltage.				±25%
	High	SIZE	DIELECTRIC	RATED	CAPACITANE		RATED VOL.	D.F.
	Temperature			VOLTAGE	RANGE	_	100V	≤7.5%
15.	Load	GML04	X5R	6.3V	C ≥ 1.0 µF		25V, 16V	≤15%
	(Endurance)	GML21	X5R I X7R	≤10V	C ≥ 10 µF		10V	≤20%
		at 150°C f	nitial measurement (Cor 1hr then set for 24 DF(Q) / I.R. Measure	4±2 hrs at room	temp.		50V, 6.3V	≤30%
			en set for 24±2 hrs at	33 27	- I.R.: 1G	Ω or RxC≥10Ω-F which	hever is smaller.	

TAPE AND REEL DIMENSION



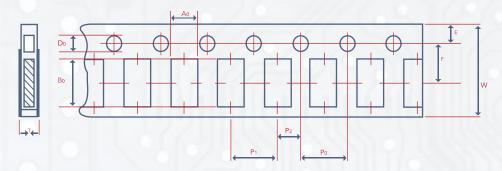
SIZE		0402, 0603, 0805, 1206, 1210	
REEL SIZE	7"	10"	13"
С	13.0±0.5	13.0±0.5	13.0±0.5
W ₁	10.0±1.5	10.0±1.5	10.0±1.5
Α	178.0±2.0	250.0±2.0	330.0±2.0
N	60.0+1.0/-0	50 min	50 min



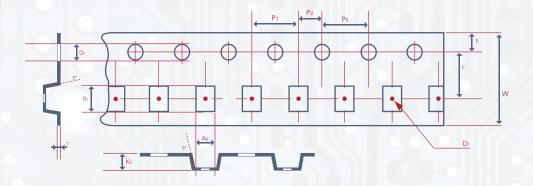


TAPE AND REEL DIMENSIONS

-The dimension of paper tape



-The dimension of plastic tape

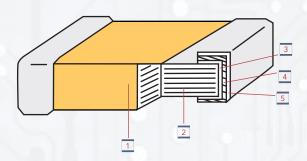


SIZE	0402	0603	0805	12	06	12	10
THICKNESS	L	Н	Т	Т	J	Т	К
A ₀	0.70 ± 0.20	1.05 ± 0.30	1.50 ± 0.20	1.90 ± 0.50	<2.00	<3.05	<3.05
B ₀	1.20 ± 0.20	1.80 ± 0.30	2.30 ± 0.20	3.50 ± 0.50	<3.70	<3.80	<3.80
Т	≤0.80	≤1.20	≤1.20	≤1.20	0.23 ± 0.1	0.23 ± 0.1	0.23 ± 0.1
K ₀		11-16	74-17	6 -	<2.00	<1.50	<2.50
W	8.00 ± 0.30	8.00 ± 0.30	8.00 ± 0.30	8.00 ± 0.30	8.00 ± 0.30	8.00 ± 0.30	8.00 ± 0.30
P ₀	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10
10XP ₀	40.00 ± 0.10	40.00 ± 0.20	40.00 ± 0.20	40.00 ± 0.20	40.00 ± 0.20	40.00 ± 0.20	40.00 ± 0.20
P ₁	2.00 ± 0.05	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10
P ₂	2.00 ± 0.05	2.00 ± 0.05	2.00 ± 0.05	2.00 ± 0.05	2.00 ± 0.05	2.00 ± 0.05	2.00 ± 0.05
D ₀	1.50 +0.1 / -0	1.50 +0.1 / -0	1.50 +0.1 / -0	1.50 +0.1 / -0	1.50 +0.1 / -0	1.50 +0.1 / -0	1.50 +0.1 / -0
D ₁		1.7	-	-	1.00 ± 0.10	1.00 ± 0.10	1.00 ± 0.10
E	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10
F	3.50 ± 0.05	3.50 ± 0.05	3.50 ± 0.05	3.50 ± 0.05	3.50 ± 0.05	3.50 ± 0.05	3.50 ± 0.05





CONSTRUCTIONS



NO.	N/	NAME			
1	Cerami	: Material	BaTiO ₃ based		
2	Inner E	lectrode	Ni		
3		Inner Layer	Cu		
4	Termination	Middle Layer	Ni		
5		Outer Layer	Sn (Matt)		

STORAGE AND HANDLING CONDITIONS

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

RECOMMENDED SOLDERING CONDITIONS

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N2 within oven are recommended.

